TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

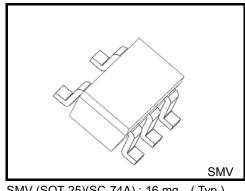
# TCK106AF, TCK107AF, TCK108AF

#### 1.0 A Load Switch IC with Slew Rate Control Driver in Small Package

The TCK106AF, TCK107AF and TCK108AF are load switch ICs for a general power management with slew rate control driver, featuring low switch ON resistance and wide input voltage operation from 1.1 to 5.5 V.

Switch ON resistance is only 63 m $\Omega$  typical at V<sub>IN</sub> = 5.0 V, I<sub>OUT</sub> = -0.5 A condition and output current is available on 1.0 A. TCK107AF and TCK108AF feature output auto-discharge function.

These devices are available in SMV (2.8 mm x 2.9 mm Typ.) package.



SMV (SOT-25)(SC-74A): 16 mg

#### **Feature**

· Low ON resistance :

 $R_{ON}$  = 63 m $\Omega$  (Typ.) at  $V_{IN}$  = 5.0 V,  $I_{OUT}$  = -0.5 A

 $R_{ON} = 71 \text{ m}\Omega$  (Typ.) at  $V_{IN} = 3.3 \text{ V}$ ,  $I_{OUT} = -0.5 \text{ A}$ 

 $R_{ON} = 101 \text{ m}\Omega$  (Typ.) at  $V_{IN} = 1.8 \text{ V}$ ,  $I_{OUT} = -0.5 \text{ A}$ 

 $R_{ON} = 175 \text{ m}\Omega$  (Typ.) at  $V_{IN} = 1.2 \text{ V}$ ,  $I_{OUT} = -0.2 \text{ A}$ 

 $R_{ON} = 223 \text{ m}\Omega$  (Typ.) at  $V_{IN} = 1.1 \text{ V}$ ,  $I_{OUT} = -0.2 \text{ A}$ 

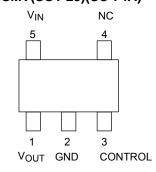
• Low Quiescent current

 $I_Q = 110 \text{ nA (Typ.)}$  at  $V_{IN} = 5.5 \text{ V}$ ,  $I_{OUT} = 0 \text{ mA}$ 

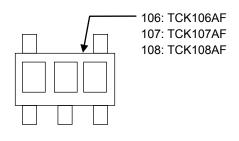
- High output current: I<sub>OUT</sub> = 1.0 A
- Wide input voltage operation: V<sub>IN</sub> = 1.1 to 5.5 V
- · Built in Slew rate control driver
- Built in Auto-discharge (TCK107AF and TCK108AF)
- Active High and Pull down connection between CONTROL and GND (TCK106AF and TCK107AF)
- Active Low (TCK108AF)
- General purpose package SMV(SOT-25) (SC-74A)

#### Pin Assignment (top view)

# SMV(SOT-25)(SC-74A)



#### Top marking



Start of commercial production 2016-01



#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating			Unit	
Input voltage	$V_{IN}$	-0.3 to 6.0		-0.3 to 6.0		V
Control voltage	V <sub>CT</sub>	-0.3 to 6.0		V		
Output voltage	V <sub>OUT</sub>		-0.3 to V <sub>IN</sub> +0.3	(Note1)	V	
Output current	lout	DC	1.0		Α	
		Pulse	1.5	(Note2)	A	
Dower dissination	D-	200 (Note3)		mW		
Power dissipation	$P_{D}$		580	(Note4)	IIIVV	
Operating temperature range	T <sub>opr</sub>	-40 to 85		°C		
Junction temeperature	Tj	150		150		
Storage temperature	T <sub>stg</sub>	-55 to 150		−55 to 150 °C		°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

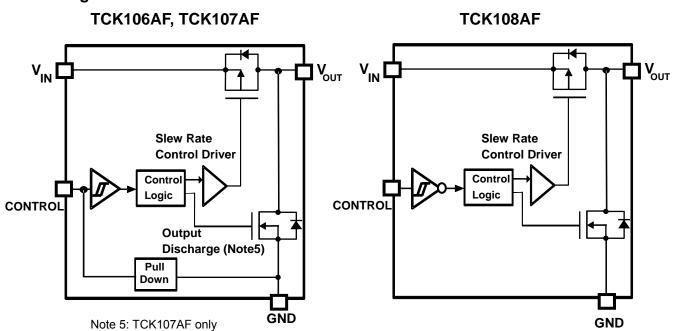
Note 1:  $V_{IN} + 0.3 \le 6.0 \text{ V}$ 

Note 2: 1 ms pulse, 1% duty cycle

Note 3: Unit Rating

Note 4: Rating at mounting on a board (FR4 board: 25.4 mm x 25.4 mm x 1.6 mm)

#### **Block Diagram**





# **Operating conditions**

Characteristics	Symbol	Condition	Min	Max	Unit
Input voltage	V <sub>IN</sub>	_	1.1	5.5	V
Output current	lout	_		1.0	Α
CONTROL High-level input voltage	V <sub>IH</sub>	111/21/2551/	0.9	_	V
CONTROL Low-level input voltage	V <sub>IL</sub>	1.1 V ≤ V <sub>IN</sub> ≤ 5.5 V		0.4	V

## **Electrical Characteristics**

# DC Characteristics (Ta = -40 to 85°C)

Characteristics	Symbol	Test Condition		Min	Тур.	Max	Unit
Quiescent current (ON state)	IQ	$V_{IN} = V_{CT} = 5.5 \text{ V},$ $I_{OUT} = 0 \text{ mA}$	TCK106AF TCK107AF	_	110	230	nA
		V <sub>IN</sub> = 5.5 V, V <sub>CT</sub> = 0 V, I <sub>OUT</sub> = 0 mA	TCK108AF				
Standby current (OFF state)	I <sub>Q(OFF)</sub>	$V_{IN}$ = 5.5 V, $V_{CT}$ = 0 V, $V_{OUT}$ = OPEN (Note6)	TCK106AF TCK107AF		65	150	nA
		$V_{IN} = V_{CT} = 5.5 \text{ V},$ $V_{OUT} = \text{OPEN}$ (Note6)	TCK108AF				
OFF-state switch current	I <sub>SD(OFF)</sub>	V <sub>IN</sub> = 5.5 V, V <sub>CT</sub> = 0 V, V <sub>OUT</sub> = GND	TCK106AF TCK107AF	_	14	1000	nA
		V <sub>IN</sub> = V <sub>CT</sub> = 5.5 V, V <sub>OUT</sub> = GND	TCK108AF				
On resistance	R <sub>ON</sub>	$V_{IN} = 5.0 \text{ V}, I_{OUT} = -0.5 \text{ A}$		_	63	90	
		V <sub>IN</sub> = 3.3 V, I <sub>OUT</sub> = -0.5 A		_	71	105	
		V <sub>IN</sub> = 1.8 V, I <sub>OUT</sub> = -0.5 A		_	101	155	mΩ
		V <sub>IN</sub> = 1.2 V, I <sub>OUT</sub> = -0.2 A		_	175	270	
		V <sub>IN</sub> = 1.1 V, I <sub>OUT</sub> = -0.2 A		_	223	_	
Discharge on resistance	R <sub>SD</sub>	<ul> <li>(TCK107AF and TCK1</li> </ul>	_	100	_	Ω	

Note 6: Except  $I_{SD(OFF)}$  OFF-state switch current



# **AC Characteristics (Ta = 25°C)**

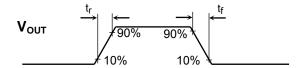
## $V_{IN} = 1.2 V$

Characteristics	Symbol	Test Condition (Figure 1)		Min	Тур.	Max	Unit
V <sub>OUT</sub> rise time	t <sub>r</sub>	$R_L = 500 \Omega$ , $C_L = 0.1 \mu F$		_	290	_	μS
V <sub>OUT</sub> fall time	t <sub>f</sub>	$R_L$ = 500 Ω, $C_L$ = 0.1 μF	TCK107AF TCK108AF	_	30	_	μs
			TCK106AF	_	104	_	
Turn on delay	toN	$R_L$ = 500 Ω, $C_L$ = 0.1 μF		_	305	_	μS
Turn off delay	t <sub>OFF</sub>	$R_L$ = 500 Ω, $C_L$ = 0.1 μF		_	5	_	μS

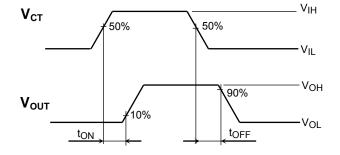
#### $V_{IN} = 3.3 V$

Characteristics	Symbol	Test Condition (Figure 1)		Min	Тур.	Max	Unit
V <sub>OUT</sub> rise time	t <sub>r</sub>	$R_L$ = 500 Ω, $C_L$ = 0.1 μF		_	130	_	μS
V <sub>OUT</sub> fall time	t <sub>f</sub>	$R_L = 500 \Omega$ , $C_L = 0.1 \mu F$	TCK107AF TCK108AF	_	25	_	μS
			TCK106AF	1	110	I	
Turn on delay	ton	R <sub>L</sub> = 500 $\Omega$ , C <sub>L</sub> = 0.1 $\mu$ F		1	100	1	μS
Turn off delay	toff	$R_L$ = 500 Ω, $C_L$ = 0.1 μF		_	10		μS

## **AC Waveform**



# TCK106AF, TCK107AF



#### TCK108AF

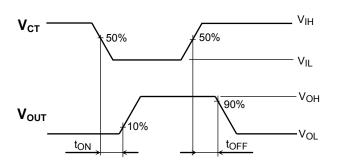
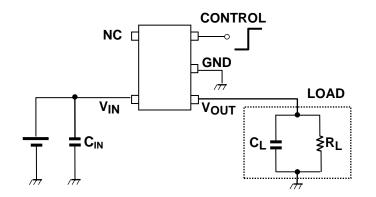


Figure 1  $t_r$ ,  $t_f$ ,  $t_{ON}$ ,  $t_{OFF}$  Waveforms

#### **Application Note**

#### 1. Application circuit example (top view)

The figure below shows the recommended configuration for TCK106AF, TCK107AF and TCK108AF.



Part number	Control voltage	IC Operation
TCK106AF TCK107AF	HIGH	ON
	LOW	OFF
	OPEN	OFF
TCK108AF	HIGH	OFF
	LOW	ON

#### 1) Input capacitor

An input capacitor ( $C_{IN}$ ) is not necessary for the guaranteed operation of TCK106AF, TCK107AF and TCK108AF. However, it is recommended to use input capacitors to reduce voltage drop due to sharp changes in output current and also for improved stability of the power supply. When used, place  $C_{IN}$  as close to  $V_{IN}$  pin to improve stability of the power supply. Also, due to the  $C_{IN}$  selected,  $V_{IN} < V_{OUT}$  may occur, causing a reverse current to flow through the body diode of the pass-through p-ch MOSFET of the load switch IC. In this case, a higher value for  $C_{IN}$  as compared to  $C_{L}$  is recommended.

#### 2) Output capacitor

An output capacitor ( $C_{OUT}$ ) is not necessary for the guaranteed operation of TCK106AF, TCK107AF and TCK108AF. However, there is a possibility of overshoot or undershoot caused by output load transient response, board layout and parasitic components of load switch IC. In this case, an output capacitor with  $C_{OUT}$  more than  $0.1\mu F$  is recommended.

#### 3) Control pin

A control pins for TCK106AF and TCK107AF are both Active High and TCK108AF is Active Low. These controls both the pass-through p-ch MOSFET and the discharge n-ch MOSFET (except TCK106AF), operated by the control voltage and Schmitt trigger. When the control voltage level is High (Low; TCK108AF), p-ch MOSFET is ON state and n-ch MOSFET is OFF state. When control voltage level is Low (High; TCK108AF), and the state of the MOSFETs is reversed. Also, pull down resistance equivalent to a few M $\Omega$  is connected between CONTROL and GND, thus the load switch IC is in OFF state even when CONTROL pin is OPEN(except TCK108AF). In addition, CONTROL pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

#### 2. Power Dissipation

Both unit and board-mounted power dissipation ratings for TCK106AF, TCK107AF and TCK108AF are available in the Absolute Maximum Ratings table.

Power dissipation is measured on the board shown below.

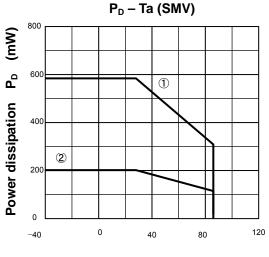
①: Rating at mounting on a board

Board material: FR4 board

Board dimension: 25.4 mm × 25.4 mm × 1.6 mm

Copper area: 645 mm<sup>2</sup>

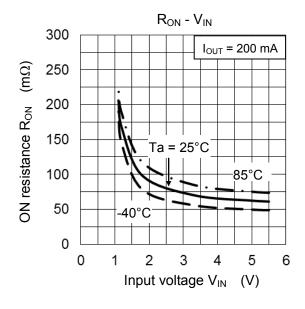
2: Unit Rating

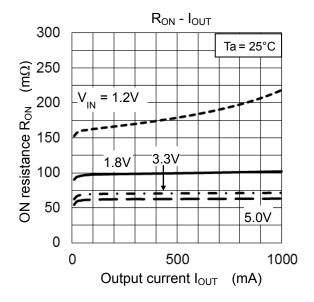


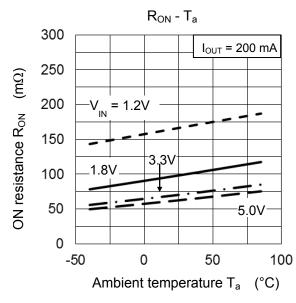
Ambient temperature Ta (°C)

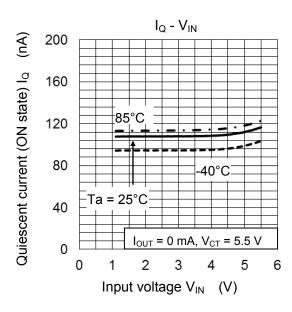
Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc and applying the appropriate derating for allowable power dissipation during operation.

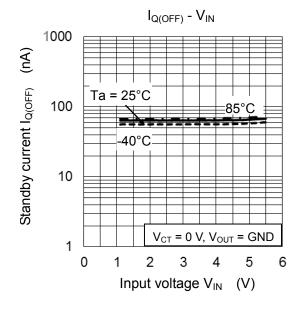
# **Representative Common Characteristics**

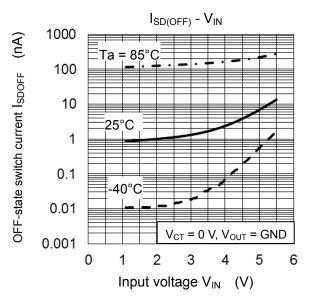




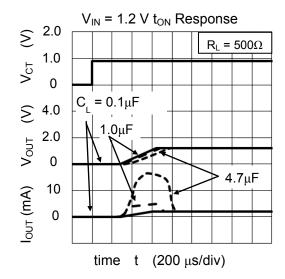


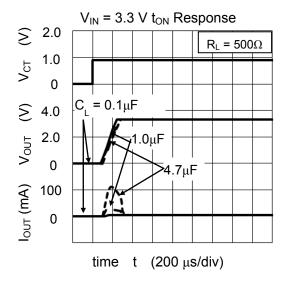


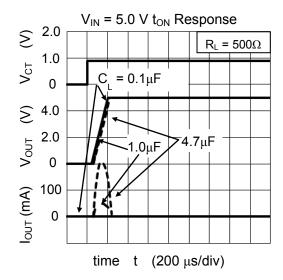




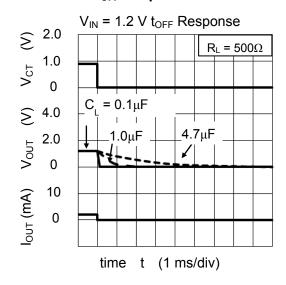
# TCK107AF toN Response

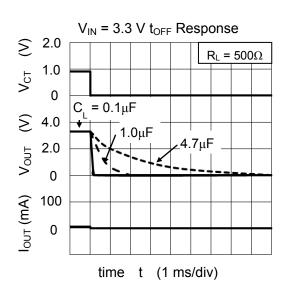


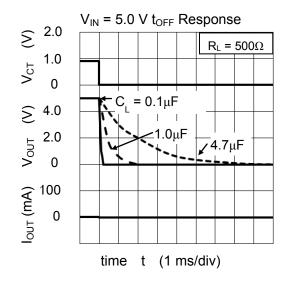




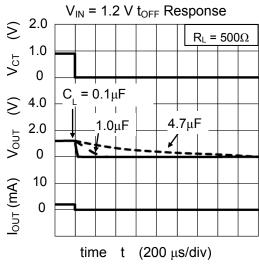
#### TCK106AF toff Response

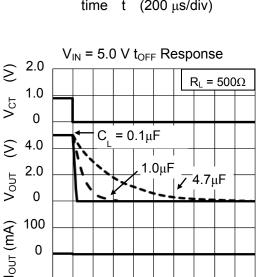




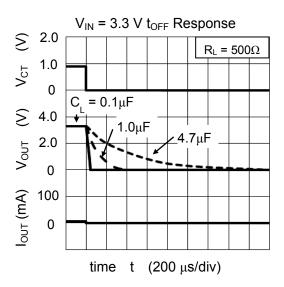


#### TCK107AF toff Response





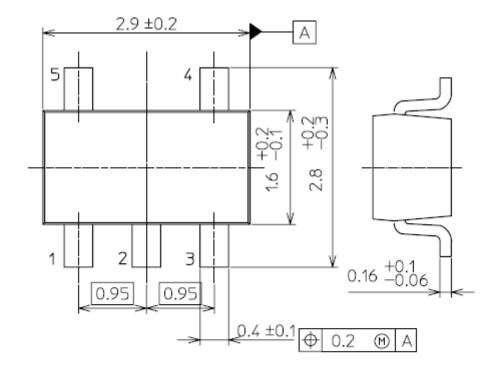
time t (200  $\mu$ s/div)

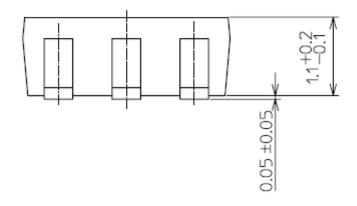


# Package dimension

# SMV (SOT-25)(SC-74A)



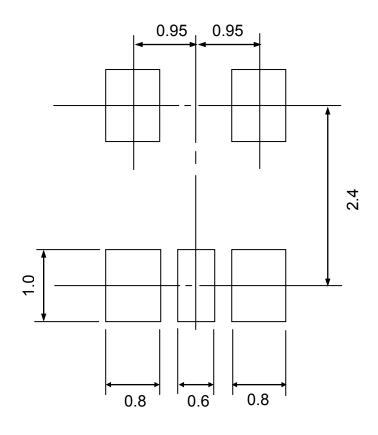




Weight: 16mg (Typ.)

Land pattern dimensions (for reference only)

Unit: mm



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